EMI Ferrite Bead



BBPY Series







Overview

EMI ferrite beads are made of ferrite material, which can block high-frequency noise while allowing required signals to pass through, providing high impedance and noise attenuation to improve signal integrity/efficiency and reduce power loss.

Benefits

- 1. For Power Line
- 2. Compliance with EMI regulations.
- 3. Reduced power loss and improved system efficiency
- 4. Operating temperature range: -55 ~ +125°C
- 5. Improved signal integrity

Applications

- 1. Wearable device
- 2. Industrial
- 3. Communications
- 4. Consumer Electronics

Product Information

Series	Size Code (JIS/EIA)	Impedance (Ω)
BBPY	0603/0201 1005/0402 1608/0603 2012/0805	10 ~ 1500
	3216/1206 4532/1812	

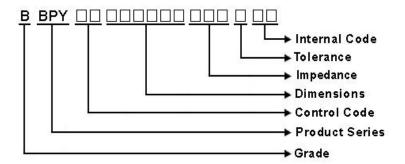








- 1 Scope: This specification applies to MULTILAYER FERRITE CHIP BEADS
- 2 Part Numbering:



3 Rating:

Operating Temperature: -55°C ~ 125 °C(Including self - temperature rise)

Storage Temperature: $-55^{\circ}\text{C} \sim 125^{\circ}\text{C}(\text{after PCB})$

- 5 °C~ 4 0 °C, Humidity 4 0 %~ 7 0 % (before PCB)

4 Marking:

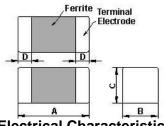
No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



6 Configuration and Dimensions:



Dimensions in mm		
TYPE	160808	
Α	1.6±0.15	
В	0.8±0.15	
С	0.8±0.15	
D	0.3±0.20	

Net Weight (grms)	
Size Code	Net Weight (grms)
160808	0.00576

7 Electrical Characteristics:

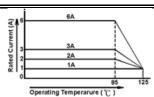
				Rated
Part No.	Impedance	Test Freq.	RDC	Current
	(Ω)		(Ω)Max.	(mA)Max.
BBPY00160808100 = 00	10	100 MHz,200 mV	0.02	4000
BBPY00160808110 = 00	11	100 MHz,200 mV	0.02	4000
BBPY00160808190 = 00	19	100 MHz,200 mV	0.03	3000
BBPY00160808220 00	22	100 MHz,200 mV	0.03	3000
BBPY00160808250 00	25	100 MHz,200 mV	0.03	3000
BBPY00160808260 00	26	100 MHz,200 mV	0.03	3000
BBPY00160808300 00	30	100 MHz,200 mV	0.03	3000
BBPY00160808330 00	33	100 MHz,200 mV	0.035	3000
BBPY00160808400 00	40	100 MHz,200 mV	0.035	3000
BBPY00160808470 00	47	100 MHz,200 mV	0.04	3000
BBPY00160808500 00	50	100 MHz,200 mV	0.04	3000
BBPY00160808600 00	60	100 MHz,200 mV	0.04	3000
BBPY00160808680 00	68	100 MHz,200 mV	0.05	2500
BBPY00160808700 00	70	100 MHz,200 mV	0.05	2500
BBPY00160808750 00	75	100 MHz,200 mV	0.05	2500
BBPY00160808800 00	80	100 MHz,200 mV	0.05	2500
BBPY00160808101□00	100	100 MHz,200 mV	0.05	2500
BBPY00160808121 00	120	100 MHz,200 mV	0.08	2500
BBPY00160808151 00	150	100 MHz,200 mV	0.085	2000
BBPY00160808181 00	180	100 MHz,200 mV	0.09	2000
BBPY00160808201□00	200	100 MHz,200 mV	0.095	2000
BBPY00160808221□00	220	100 MHz,200 mV	0.1	2000
BBPY00160808241□00	240	100 MHz,200 mV	0.12	1500
BBPY00160808301□00	300	100 MHz,200 mV	0.12	1500
BBPY00160808331□00	330	100 MHz,200 mV	0.12	1500

NOTE: □-tolerance Y=±25% / T=±30%

1. Operating temperature range - 5 5 $^{\circ}$ C ~ 1 2 5 $^{\circ}$ C(Including self - temperature rise)

2.Rate Current : Applied the current to coils, the temperature rise shall not be more than 30°C

3.As for BBPY type. Rated Current is derated as right figure depending on the operating temprature.



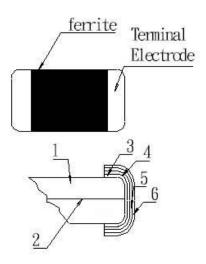


Part No.	Impedance (Ω)	Test Freq.	RDC (Ω)Max.	Rated Current (mA)Max.
BBPY00160808471 00	470	100 MHz,200 mV	0.15	1500
BBPY00160808601 00	600	100 MHz,200 mV	0.2	1000
BBPY00160808102 ₀ 00	1000	100 MHz,200 mV	0.25	800
BBPY00160808122 ₀ 00	1200	100 MHz,200 mV	0.25	800
BBPY00160808152000	1500	100 MHz,200 mV	0.4	500



8 BBPY00160808 Series

8.1 Construction:



8.2 Material List:

No	Part	Material
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn



9 Reliability Of Ferrite Multilayer Chip Bead

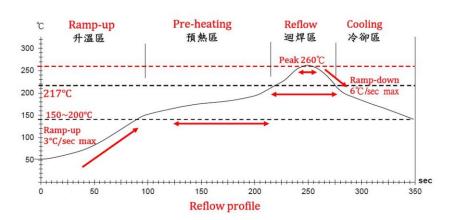
1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	Deflection: 2.0mm
		ferrite	Keeping Time: 30sec
			*For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate
			Oscillation Frequency: 10 to 55 to 10Hz for 1min
			Amplitude: 1.5mm
			Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
		More than 75% of the termina	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5°C
		with solder.	Immersion Time: 10±1sec
		Impedance : within ±30% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150°C, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245±5°C (Pb-Free)
			Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination	Test device shall be soldered on the substrate,
		Chip	then apply a force in the direction of the arrow.
		F	Force: 5N
			Keeping Time: 10±1sec
		Mounting Pad	

1-2.Environmental Performance

No	Item	Specification		Test Method	•
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:		
		Impedance: within±30% of	Step	Temperature (°ℂ)	Time (min)
		initial value	1	-55±3	30
			2	25±2	3
			3	125±3	30
			4	25±2	3
			Total: 100d	cycles	
			Measured	after exposure in the room cor	ndition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2°C		
			Relative H	umidity: 90 ~ 95% / Time: 100	0hrs
			Measured	after exposure in the room cor	ndition for 24hrs
1-2-3	High		Temperatu	ıre: 125±3°€ / Relative Humidi	ty: 0%
	Temperature Resistance		Applied Current: Rated Current /Time: 1000hrs		
			Measured	after exposure in the room cor	ndition for 24hrs
1-2-4	Low		Temperatu	ıre: -55±3°ℂ	
	Temperature Resistance		Relative H	umidity: 0% / Time: 1000hrs	
			Measured	after exposure in the room cor	ndition for 24hrs





Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150°C	150°C ~ 200°C	Above 217°C	260±5°C	Peak Temp.~150℃
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	-	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	-

NOTE:

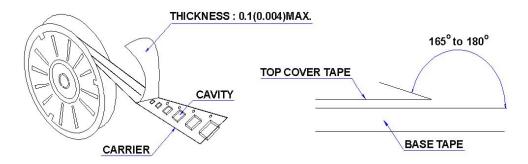
- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow
- 3. Products can only be soldered with reflow



10 Packaging:

10.1 Packaging -Cover Tape

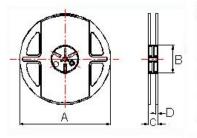
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



10.2 Packaging Quantity

TYPE	PCS/REEL
060303	15000
100505	10000
160808	4000
201209	4000

10.3 Reel Dimensions

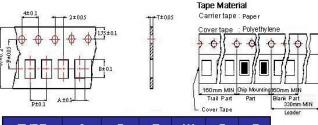


TYPE	Α	В	C	D
060303	178	60	12	1.5
100505	178	60	12	1.5
160808	178	60	12	1.5
201209	178	60	12	1.5



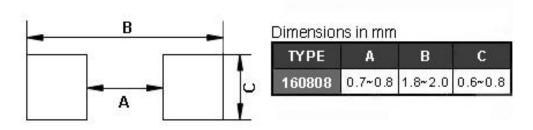
10 Packaging:

10.4 Tape Dimensions in mm



TYPE	A	В	T	W	P	F
060303	0.37	0.67	0.42	8	2	3.5
100505	0.62	1.12	0.60	8	2	3.5
160808	1.05	1.85	0.95	8	4	3.5
201209	1.50	2.30	0.97	8	4	3.5

11 Recommended Land Pattern:



12 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
- 5. The moisture sensitivity level (MSL) of products is classified as level 1.



